

### Product Summary

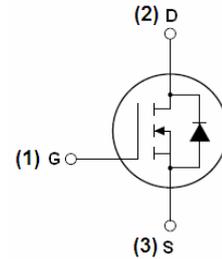
Part #	$V_{DS}$	$R_{DS(on).typ}$ (@ $V_{GS}=10V$ )	$R_{DS(on).typ}$ (@ $V_{GS}=4.5V$ )	$I_D$
EFM025N03D	30V	2.5m $\Omega$	3.6 m $\Omega$	120A

### Description

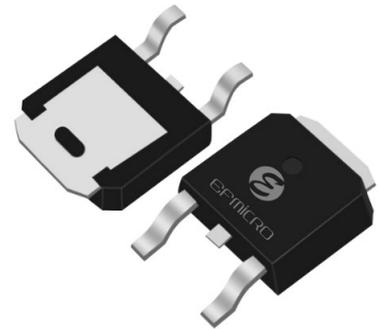
- The EFM025N03D is the high cell density trenched
- N-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM025N03D meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

### Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



N-Channel MOSFET



TO-252-2L

### Ordering Information:

Part NO.	EFM025N03D
Marking	025N03D****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

### Absolute Maximum Ratings ( $T_C=25^\circ C$ )

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	120	A
Drain Current-Pulsed <sup>(Note 1)</sup>	$I_{DM}$	480	A
Maximum Power Dissipation	$P_D$	88	W
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	333	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JC}$	1.4	$^\circ C/W$
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• Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

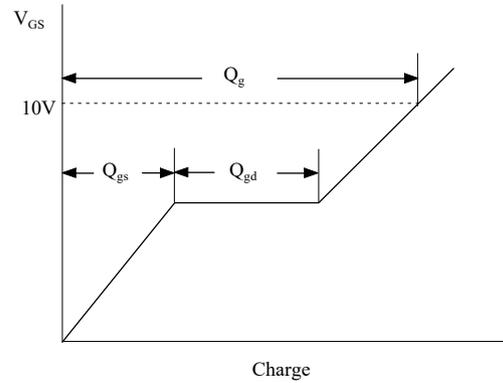
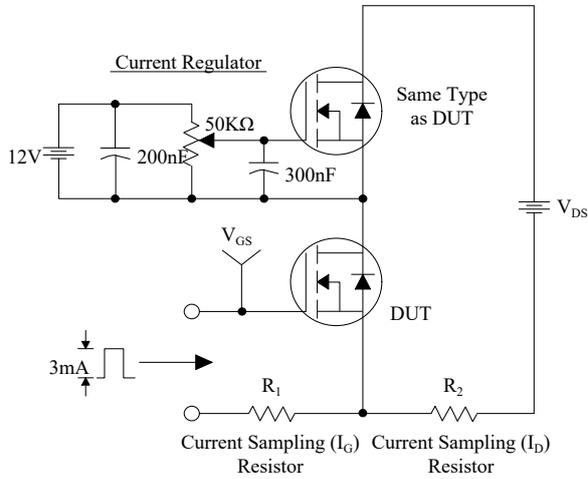
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	30	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V V <sub>GS</sub> =0V	--	--	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V V <sub>DS</sub> =0V	--	--	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250uA	1.0	1.5	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V I <sub>D</sub> =20A	--	2.5	3.1	mΩ
		V <sub>GS</sub> =4.5V I <sub>D</sub> =15A	--	3.6	4.5	mΩ
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V V <sub>GS</sub> =0V F=1.0MHz	--	4000	--	PF
Output Capacitance	C <sub>oss</sub>		--	437	--	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		--	396	--	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V I <sub>D</sub> =30A V <sub>GS</sub> =10V R <sub>L</sub> =3Ω,	--	14	--	nS
Turn-on Rise Time	t <sub>r</sub>		--	18	--	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		--	40	--	nS
Turn-Off Fall Time	t <sub>f</sub>		--	12	--	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V I <sub>D</sub> =30A V <sub>GS</sub> =10V	--	72	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	46	--	nC
Gate-Drain Charge	Q <sub>gd</sub>		--	13	--	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V I <sub>S</sub> =1A	--	--	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		--	--	100	A

Note :

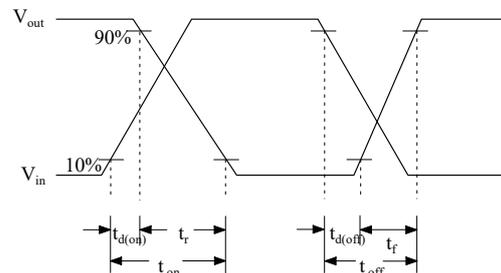
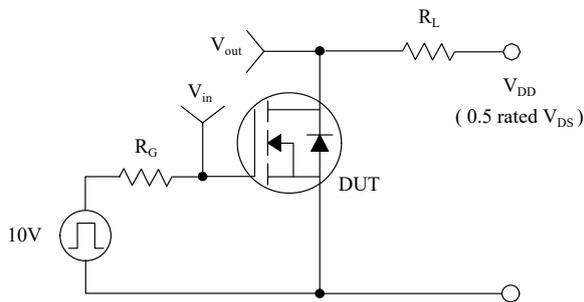
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=15V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=25A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

• Test Circuit

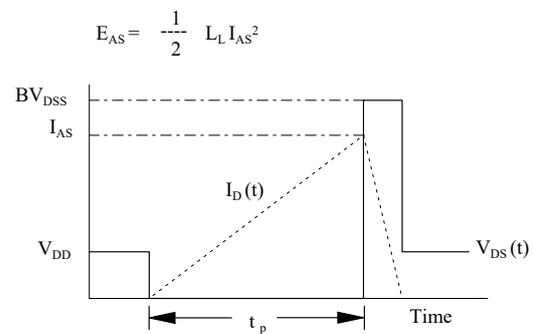
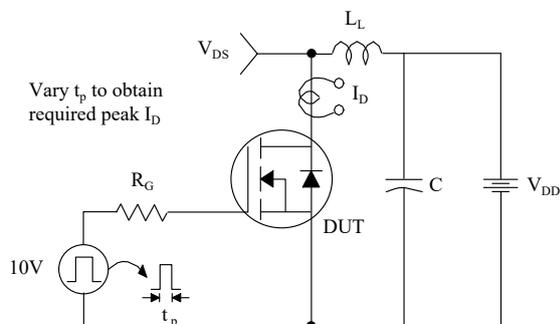
## Gate Charge Test Circuit & Waveform



## Resistive Switching Test Circuit & Waveforms



## Unclamped Inductive Switching Test Circuit & Waveforms



• Typical Characteristics

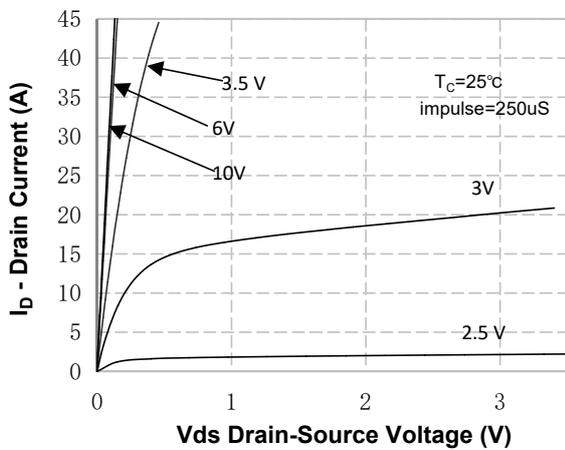


Figure 1. On-Region Characteristics

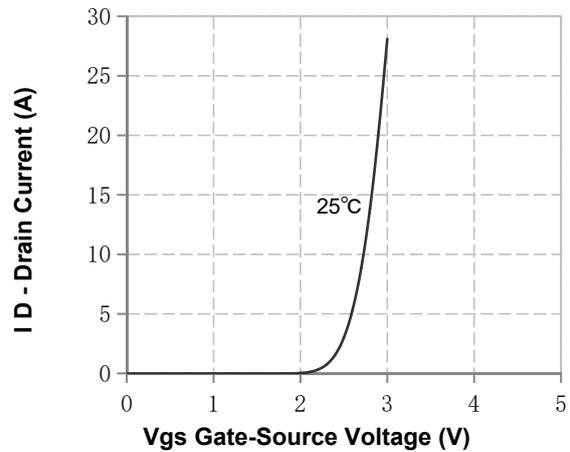


Figure 2. Transfer Characteristics

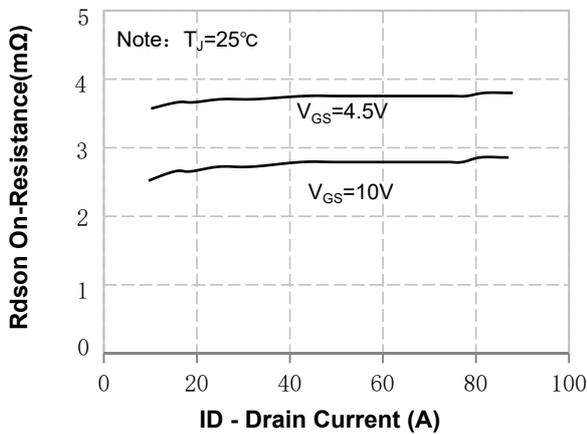


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

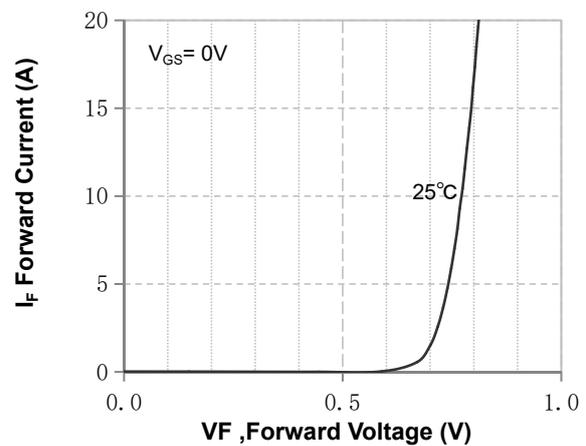


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

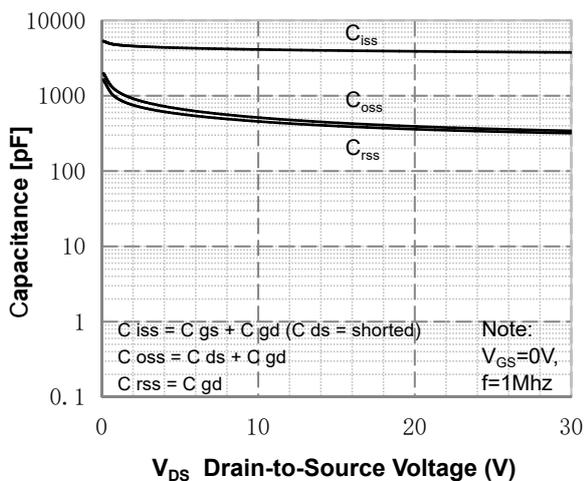


Figure 5. Capacitance Characteristics

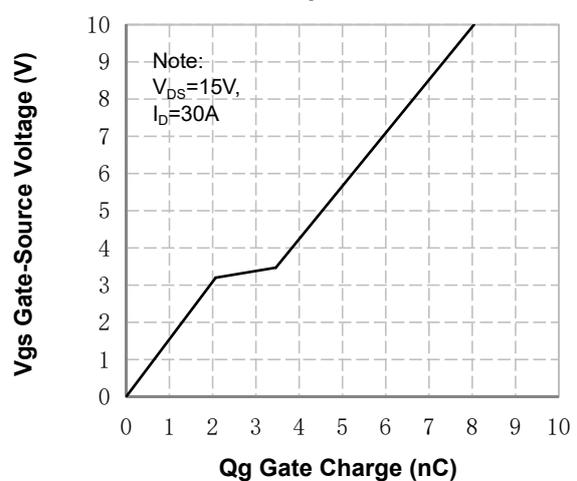
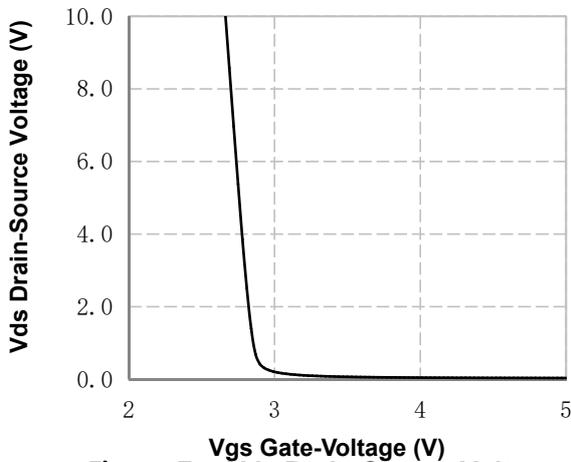
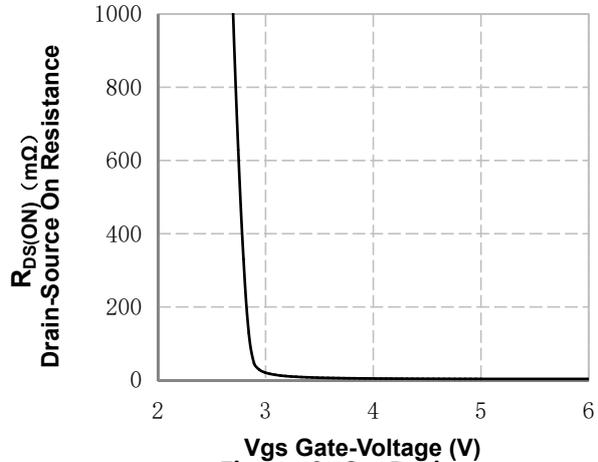


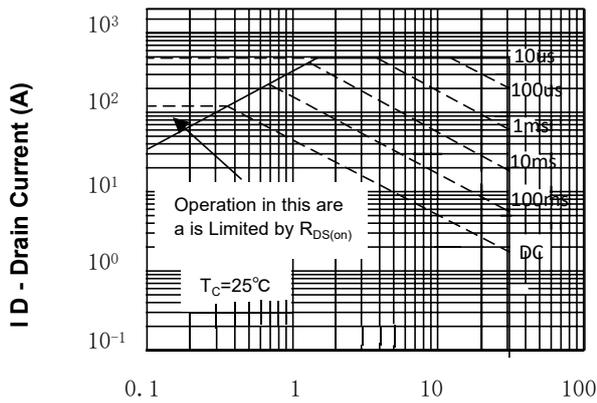
Figure 6. Gate Charge Characteristics



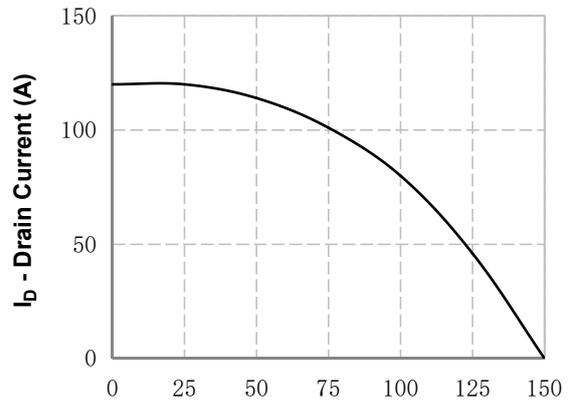
**Figure 7. Vds Drain-Source Voltage vs Gate Voltage**



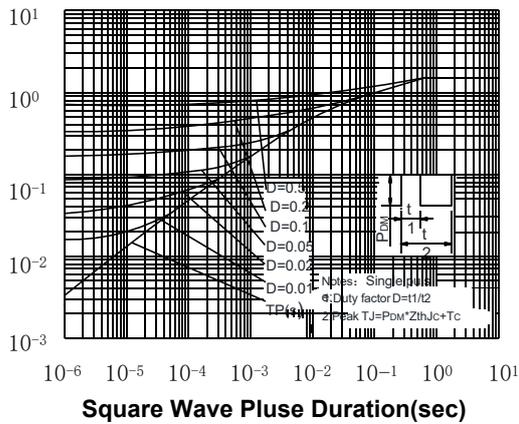
**Figure 8. On-Resistance vs Gate Voltage**



**Figure 9. Maximum Safe Operating Area**

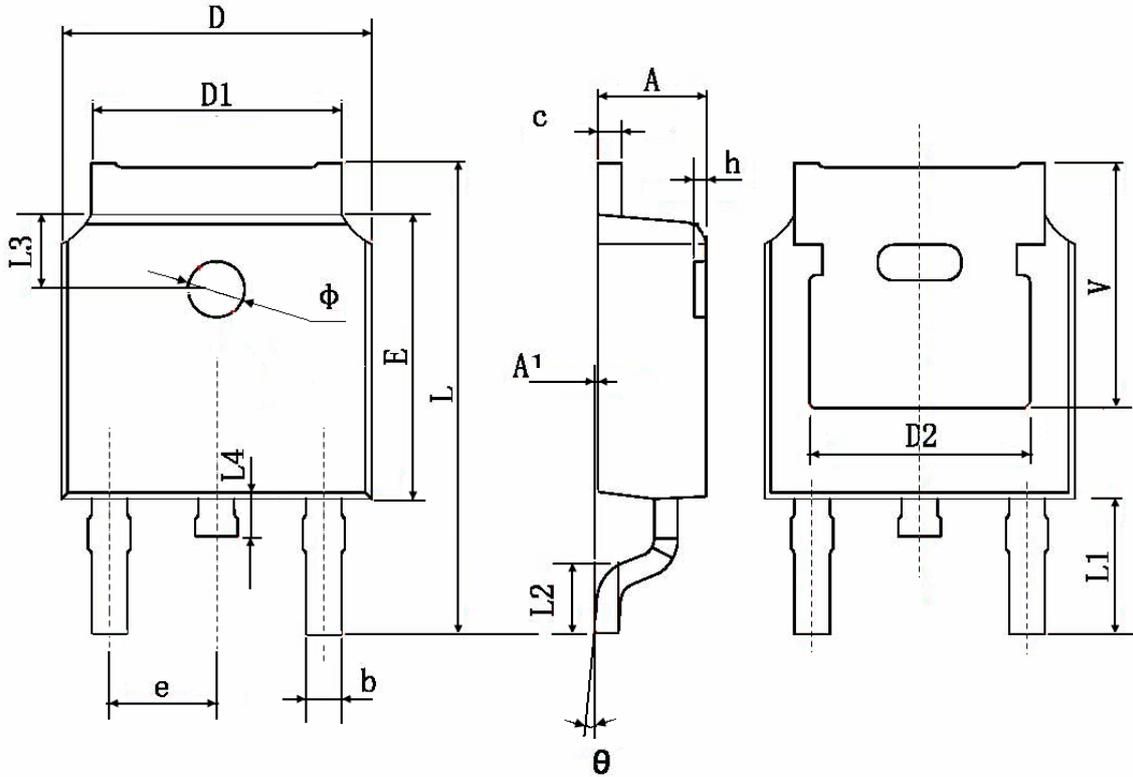


**Figure 10. Maximum Continuous Drain Current vs Temperature**



**Figure 11. Transient Thermal Response Curve**

## TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.83 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	